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(12) United States Design Patent

Enderlein et al.

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(54) **CIRCUIT BOARD**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

Nov. 1, 2002 (DE) 4 02 09 145

(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Search** D13/182; 29/829, 29/843; 174/250, 260, 265; 361/720, 736, 748, 760, 761

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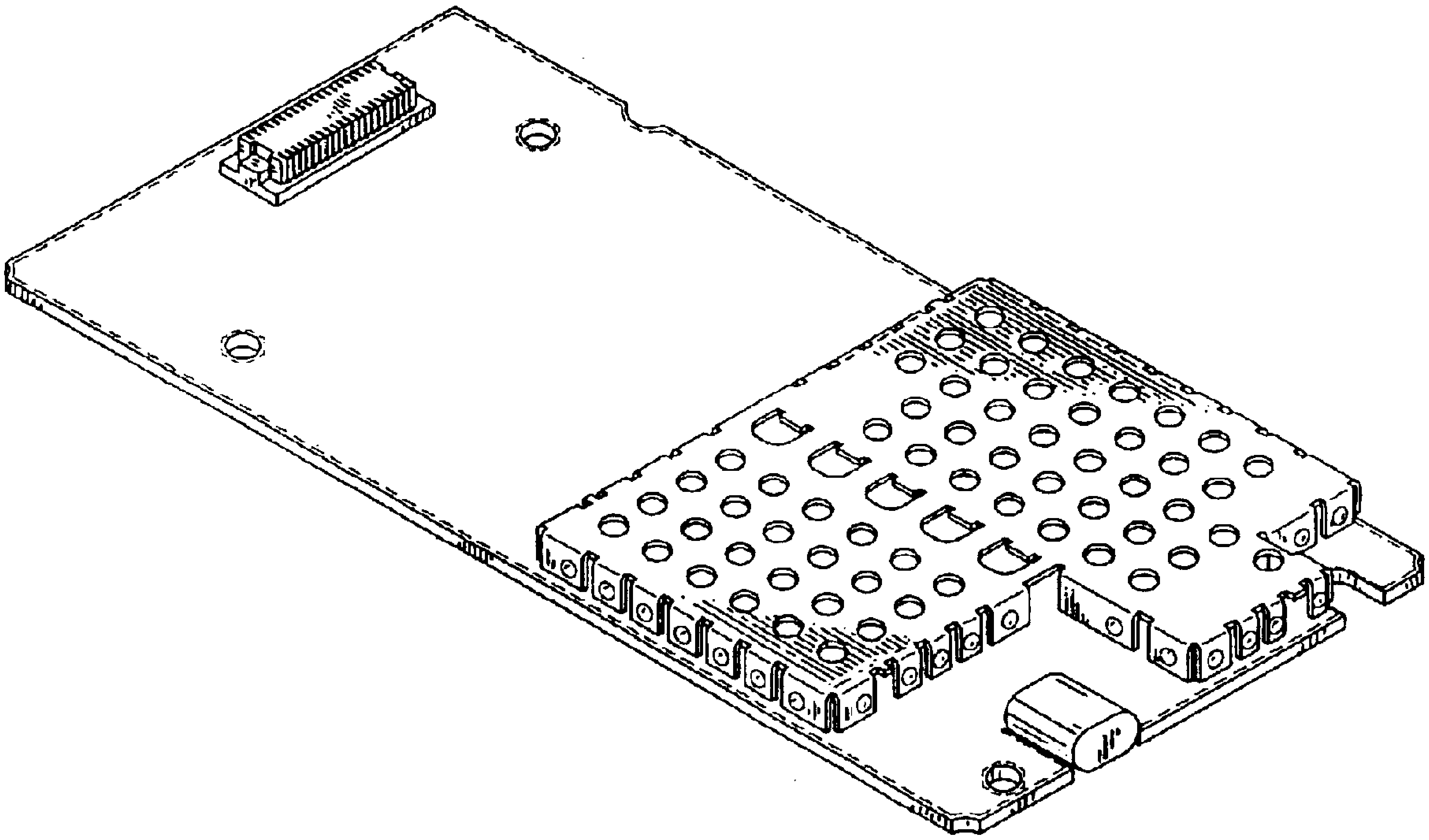
(57) CLAIM

The ornamental design for a circuit board, as shown and described.

DESCRIPTION

FIG. **1** is a front perspective of the invention.
FIG. **2** is a plan elevation of the invention.
FIG. **3** is a bottom plan of the invention.
FIG. **4** is a front elevation of the invention.
FIG. **5** is a rear elevation of the invention.
FIG. **6** is a right end elevation of the invention; and,
FIG. **7** is a left end elevation of the invention.
The broken lines define the boundary of the claimed design and form no part of the claimed design.

1 Claim, 4 Drawing Sheets



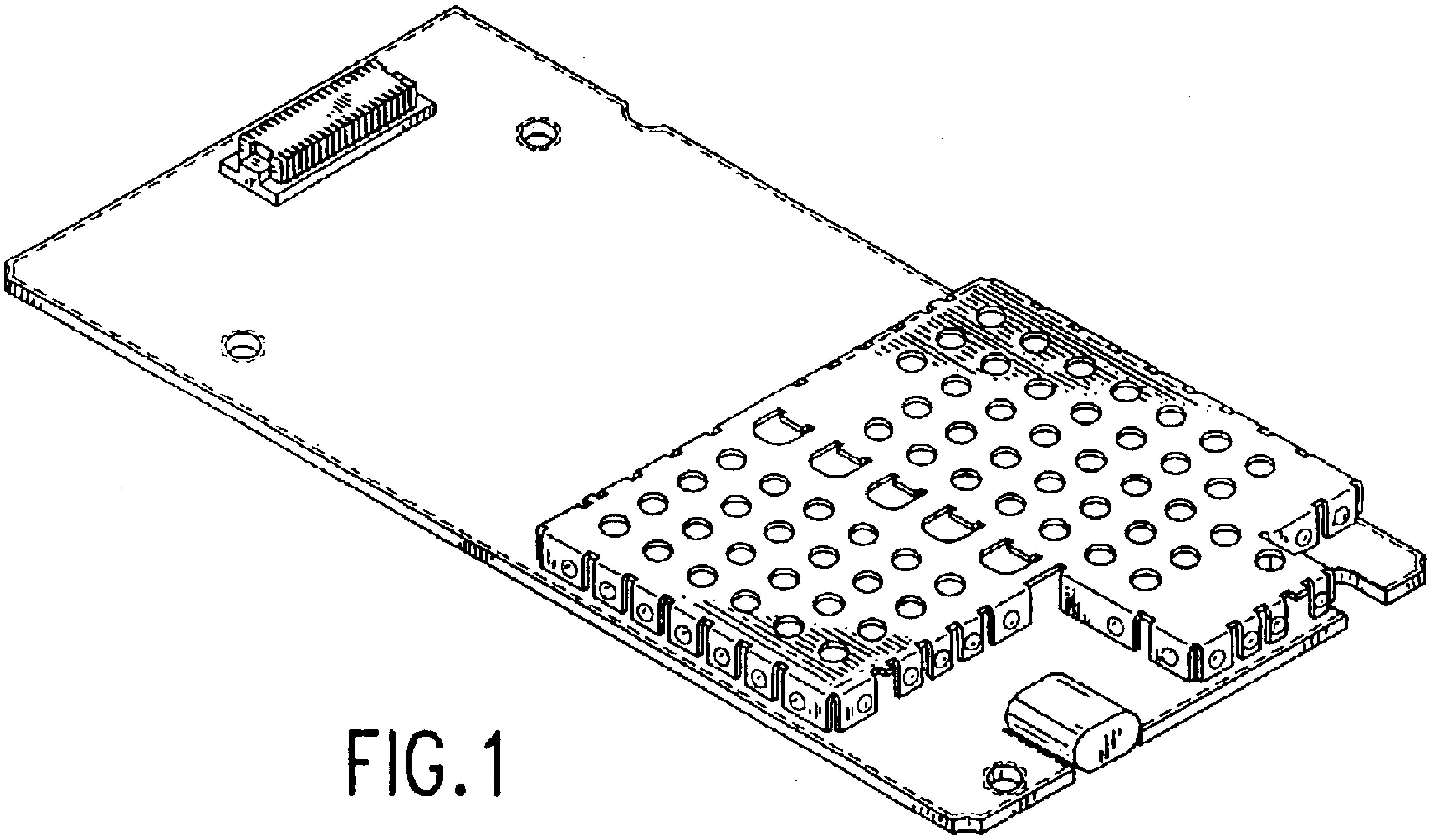


FIG.1

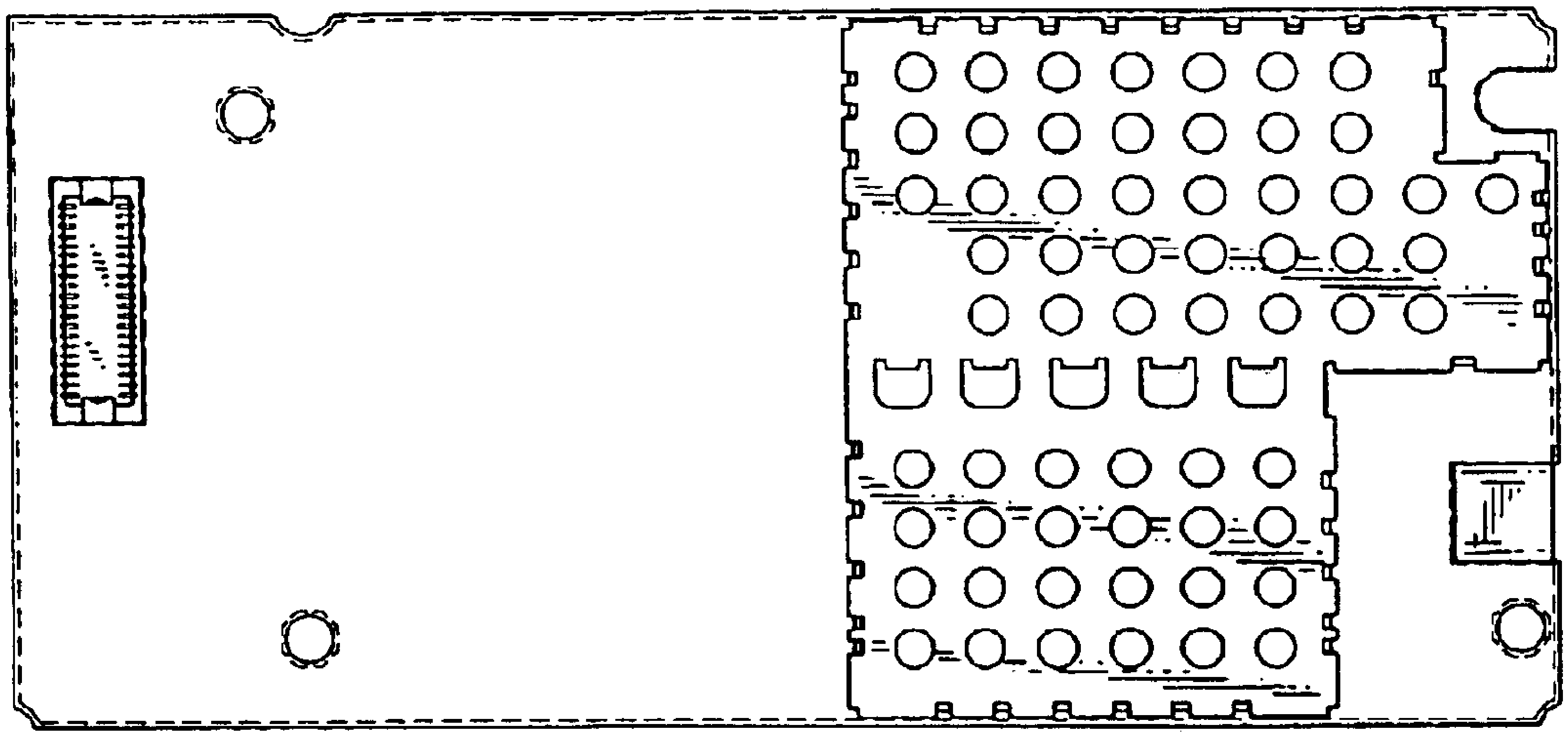


FIG.2

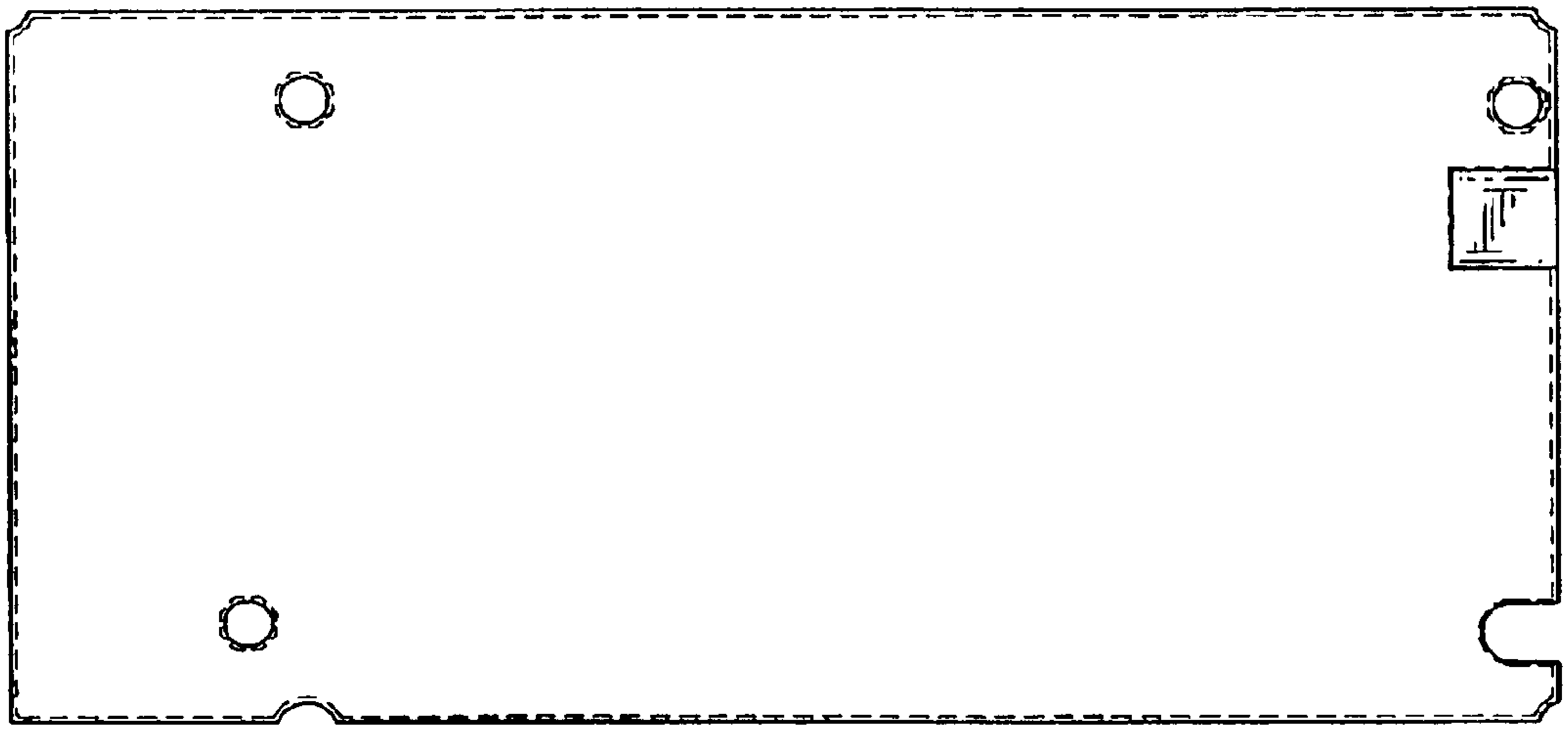


FIG.3

FIG.4

FIG.5

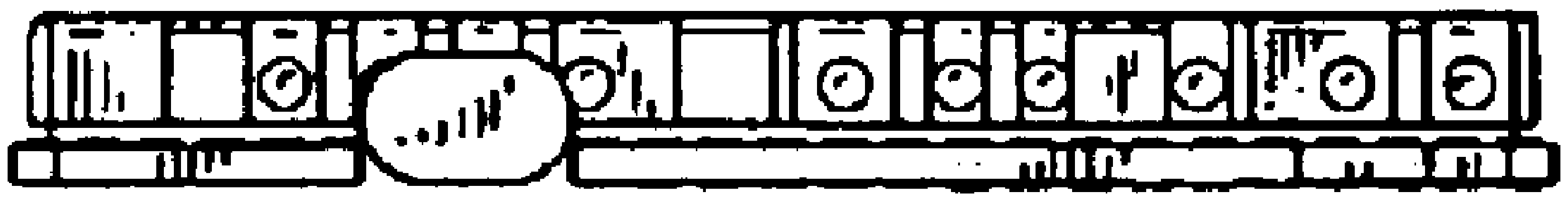


FIG.6

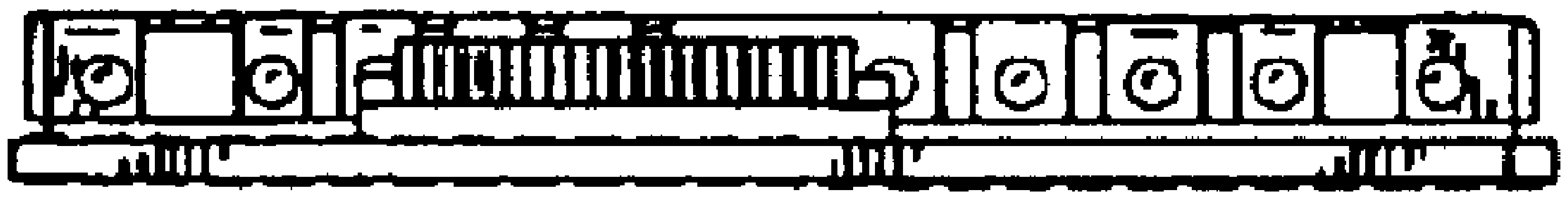


FIG.7